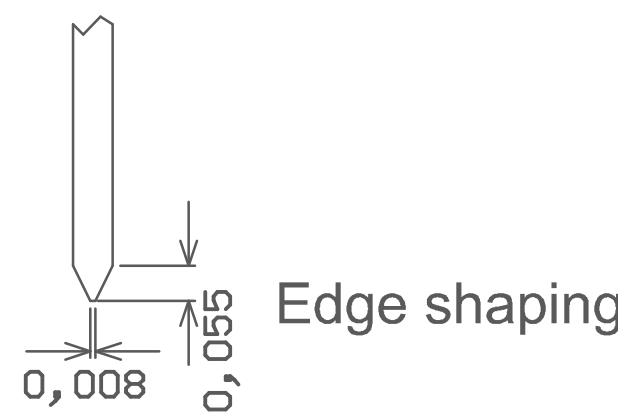


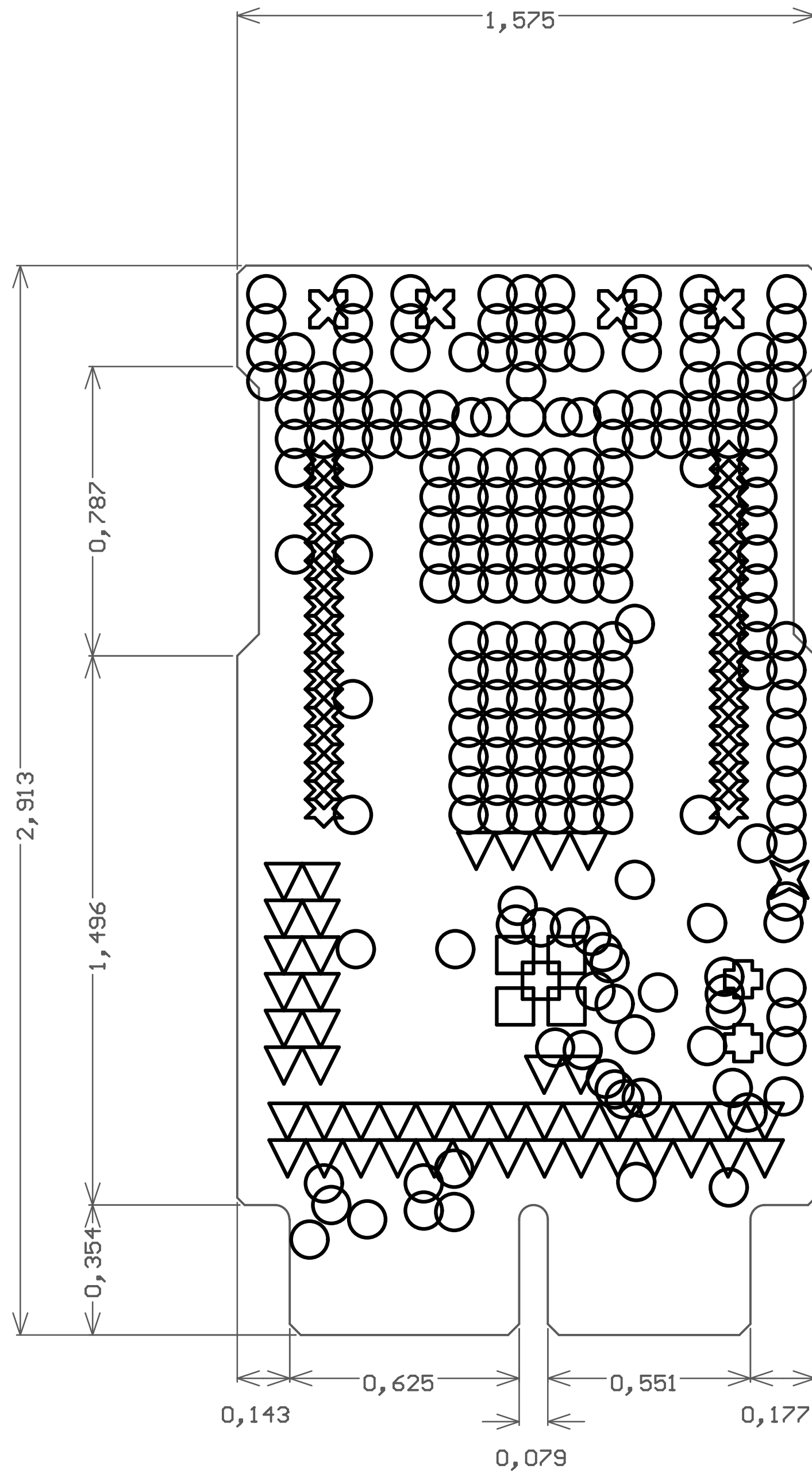
Selective hard gold on edge connector pads (top and bottom layer)



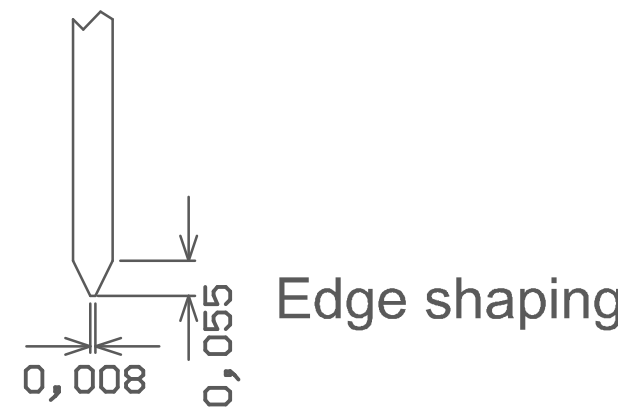
NOTES:
Specification: IPC-A-600G Class 2
No. of Layers: 4
Material: FR-4
Finished Copper Weight: 1 ounce
Thickness: 0.062" +/-0.005"
Controlled impedance: No

Soldermask: Top and Bottom Color: Green
Type: DYNACHEM EPIC 200 LPI or equivalent
Silkscreen: Top and Bottom Color: White
Finish:
Soldermask over bare copper (SMOBC) with
Electroless Nickel Immersion Gold (ENIG)
All holes to be located by the coordinates
from the NC drill data provided.
Vendor markings, date code, UL symbol and UL
rating silkscreened at an appropriate location
on bottom side.
Any alternatives to the above specifications
must be approved by Microchip Technology Inc.
Use artwork set No. 05-10409 R1.0
All dimensions are in inches.
All material to be ROHS compliant.

Product Name: <i>LoRa Technology PICtail/PICtail Plus Daughter Board</i>		
Number: 04-10409	Revision: 1.0	Fabrication
Date: 2015.02.23. Time: 15:50:09		
Author: <i>Gábor Bihari (M91504)</i>	Size: A	



Selective hard gold on edge connector pads (top and bottom layer)

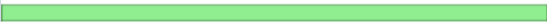







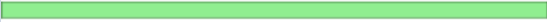


NOTES:
Specification: IPC-A-600G Class 2
No. of Layers: 4
Material: FR-4
Finished Copper Weight: 1 ounce
Thickness: 0.062" +/-0.005"
Controlled impedance: No

Soldermask: Top and Bottom Color: Green
Type: DYNACHEM EPIC 200 LPI or equivalent
Silkscreen: Top and Bottom Color: White
Finish:
Soldermask over bare copper (SMOBC) with
Electroless Nickel Immersion Gold (ENIG)
All holes to be located by the coordinates
from the NC drill data provided.
Vendor markings, date code, UL symbol and UL
rating silkscreened at an appropriate location
on bottom side.
Any alternatives to the above specifications
must be approved by Microchip Technology Inc.
Use artwork set No. 05-10409 R1.0
All dimensions are in inches.
All material to be ROHS compliant.

Symbol	Hit Count	Finished Hole Size	Plated	Hole Type
✕	1	0,900mm (35,43mil)	PTH	Round
⊗	2	0,900mm (35,43mil)	NPTH	Round
⊗	4	0,500mm (19,69mil)	PTH	Round
□	5	0,381mm (15,00mil)	PTH	Round
✱	40	0,700mm (27,56mil)	PTH	Round
▽	46	1,016mm (40,00mil)	PTH	Round
○	215	0,250mm (9,84mil)	PTH	Round
	313 Total			

Board Stack Report

Stack Up		Layer Stack			
Layer	Board Layer Stack	Name	Material	Thickness	Constant
1		Top Paste			
2		Top Overlay			
3		Top Solder	Solder Resist	0,40mil	3,5
4		Component Side	Copper	1,38mil	
5		Dielectric 1	FR-4	61,00mil	4,2
6		Bottom Layer	Copper	1,38mil	
7		Solder Side	Solder Resist	0,40mil	3,5
8		Bottom Overlay			
9		Bottom Paste			
	Height : 64,56mil				